AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

Claim 1 (Currently Amended): A method of polishing an object comprising polishing the object with a polishing fluid interposed between a polishing film and the object~~, characterized in that polishing is performed~~ while keeping ~~a~~the pH of the polishing fluid in a range of not less than 2 but less than 7 during the polishing ~~fluid is used for polishing~~, wherein the polishing fluid contains no halogen-containing acid.

Claim 2 (Currently Amended): The method according to claim 1, wherein the pH of the polishing fluid is kept in a range of not less than 2 but less than 7 during the polishing ~~fluid is used for polishing,~~ by the use of a polishing fluid with a pH thereof having been previously adjusted by a pH adjuster.

Claim 3 (Currently Amended): The method according to claim 1~~ or 2~~, wherein the pH of the polishing fluid is kept in a range of not less than 2 but less than 7 during the polishing ~~fluid is used for polishing,~~ by the use of a polishing film containing a pH adjuster as the polishing film, and having the pH adjuster dissolved into the polishing fluid during the polishing~~fluid is used for polishing~~.

Claim 4 (Currently Amended): The method according to claim 2~~ or 3~~, wherein the pH adjuster comprises a substance containing a carboxyl group.

Claim 5 (Currently Amended): A polishing film ~~having~~comprising a substrate and a polishing layer ~~that contains~~formed on the substrate layer, said polishing layer containing abrasive particles, ~~and~~ a binder resin, ~~said polishing layer formed on the substrate layer, characterized in that the polishing layer contains~~and a pH adjuster for having a pH of a polishing fluid being in a range of not less than 2 but less than 7, in which the polishing fluid is interposed between the polishing film and an object to be polished, and the pH adjuster contains no halogen-containing acid.

Claim 6 (Currently Amended): The polishing film according to claim 5, ~~characterized in that~~wherein the pH adjuster comprises a substance containing a carboxyl group.

Claim 7 (Currently Amended): The polishing film according to claim 5 ~~or 6, characterized in that,~~ wherein the substance containing the carboxyl group is ethylenediaminetetracetic acid.

Claim 8 (New): The polishing film according to claim 7, wherein the polishing layer contains the ethylenediaminetetracetic acid with a concentration of 3 to 20 wt.%.

Claim 9 (New): The polishing film according to claim 7, wherein the ethylenediaminetetracetic acid contained in the polishing layer is in a powder form with a particle size of not more than 60 μm.

Claim 10 (New): The polishing film according to claim 9, wherein the range of the particle size of the ethylenediaminetetracetic acid in the powder form is within 20 μm.

Claim 11 (New): The polishing film according to claim 5, wherein the binder resin is polyester resin.

Claim 12 (New): The polishing film according to claim 11, wherein the polyester resin is cross-linked by isocyanate and contained in the polishing layer.

Claim 13 (New): The polishing film according to claim 7, wherein the ethylenediaminetetracetic acid is in a powder form with a particle size of not more than 60 μm and the binder resin is polyester resin.

Claim 14 (New): The polishing film according to claim 13, wherein the range of the particle size of the ethylenediaminetetracetic acid in the powder form is within 20 μm.

Claim 15 (New): The polishing film according to claim 13, wherein the polyester resin is cross-linked by isocyanate and contained in the polishing layer.

Claim 16 (New): A method of manufacturing the polishing film of claim 13, comprising the steps of:

(a) applying on a substrate a solution of a mixture of polyester resin, isocyanate, abrasive particles, powdered ethylenediaminetetracetic acid having a particle size of not more than 60 μm and solvent, and

(b) heating the same, thereby allowing the polyester resin to be cross-linked by the isocyanate so as to form a polishing layer.

Claim 17 (New): The method of manufacturing the polishing film according to claim 16, wherein the range of the particle size of the powdered ethylenediaminetetracetic acid is within 20 μm.